


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	AMS/19/11709	
1.3 Title of PCN	New molding compound for TO220 package to replace SAMSUNG SDI under termination phase	
1.4 Product Category	See product list	
1.5 Issue date	2019-09-09	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	FRANCKE CHRISTIANE
2.1.2 Phone	+49 89460062128
2.1.3 Email	christiane.francke@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Lorenzo NASO
2.1.2 Marketing Manager	Salvatore DI VINCENZO
2.1.3 Quality Manager	Sergio Tommaso SPAMPINATO

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Encapsulation/sealing material	ST SHENZHEN CHINA

4. Description of change

	Old	New
4.1 Description	Molding compound = Samsung (SG-8200DTA and SI-7200DXC)	Molding compound = Replacement of current mold compounds with alternative material from different supplier
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	No impact	

5. Reason / motivation for change

5.1 Motivation	As anticipated by ST Corporate PCI No. CRP/19/11478, this PCN to announce the replacement of current Samsung SDI mold compound for TO 220 package assembled in ST SHENZHEN - CHINA Plant with alternative material from different supplier. The changed products do not present modified electrical, dimensional or thermal parameters, leaving unchanged the current information published in the product datasheet. There is no change in the packing modes and the standard delivery quantities either.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	By internal codification and traceability code
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7. Timing / schedule

7.1 Date of qualification results	2019-08-02
7.2 Intended start of delivery	2019-12-03
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	11709 W749-2019-XL05-L317-LTAD-LF05_reliability report.pdf
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8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2019-09-09
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9. Attachments (additional documentations)
11709 Public product.pdf 11709 W749-2019-XL05-L317-LTAD-LF05_reliability report.pdf

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	L7805ACV	
9756078	L7805CV	
	L7809ABV	
	L7809ABV-DG	
	L7809ACV	
	L7809CV-DG	
	L7812ACV-DG	
	L7818CV-DG	
	L78M05ABV-DG	
9756086	L78S05CV	
	L7908CV-DG	
	LD1086V-DG	
	LD1117V33C-DG	
	LD1117V50-DG	
	LF50ABV	
	LF50ABV-DG	

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